

01-14-2002



FORM PTO-1595

U.S. Department of Commerce
Patent and Trademark Office

TIJ-29147

101944895

To the Assistant Commissioner for Patents. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

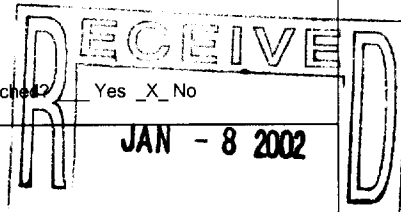
- (1) Kenji (nmi) MASUMOTO
- (2) Mutsumi (nmi) MASUMOTO
- (3) Akira (nmi) KARASHIMA
- (4) Texas Instruments Japan, Ltd.

1/8/02

2. Name and Address of receiving party(ies):

TEXAS INSTRUMENTS INCORPORATED
P.O. Box 655474, MS 3999
Dallas, TX 75265

Additional name(s) & address(es) attached? Yes No



3. Nature of Conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other _____

Execution Date: Kenji MASUMOTO, 08/08/2001; Mutsumi MASUMOTO, 08/08/2001; Akira KARASHIMA, 08/09/2001; Texas Instruments Japan, Ltd., 08/13/2001.

4. Application number(s) or patent number(s).

Execution date of the application: Kenji MASUMOTO, 08/08/2001; Mutsumi MASUMOTO, 08/08/2001; Akira KARASHIMA, 08/09/2001.

Title: A SEMICONDUCTOR DEVICE AND ITS MANUFACTURING METHOD

Docket No: TIJ-29147

A. Patent Application No.(s)

S.N. 09/909,340

B. Patent No.(s)

Additional numbers attached? Yes No

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: William B. Kempler
Senior Corporate Patent Counsel
Texas Instruments Incorporated
P. O. Box 655474, MS 3999
Dallas, TX 75265

6. Number of applications and patents involved: ____ (1) ____

7. Amount of fee enclosed or authorized to be charged: \$40

8. Deposit Account No: 20-0668, Texas Instruments Incorporated
(Attach duplicate copy if paying by deposit account)

01/14/2002 AHMED1 00000226 200668 09909340

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

William B. Kempler, Reg No. 28,228
Person Signing Document

William B. Kempler, Reg No. 28,228

10/26/01

Date

Total Number of Pages Including Cover Sheet, Attachments and Document: 3

ASSIGNMENT

WHEREAS, TEXAS INSTRUMENTS JAPAN, LTD. (hereinafter **TIJ**), a Japanese company having its headquarters at 24-1 Nishi-Shinjuku 6-chome, Shinjuku-ku, Tokyo, Japan, under the laws of Japan made application, in its own name, for Letters Patent in Japan in respect of an invention as set forth below;

WHEREAS, the or each below named inventor (hereinafter **INVENTOR**) is the or an inventor of the said invention;

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, having a place of business at 7839 Churchill Way, Mail Station 3999, Dallas, Texas 75251, USA, is desirous of acquiring the entire right, title and interest in and to the said invention outside of Japan, and in and to the U.S. patent application as identified hereinafter and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, by this Assignment, **TIJ** and **INVENTOR** sell and assign to the said **TEXAS INSTRUMENTS INCORPORATED**, its successors and assigns the entire right, title and interest in and to the said invention in the U.S.A. and all other countries outside Japan; in and to the U.S. patent application as identified below and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and the right to file applications and obtain patents in its own name in any said other country or group of countries, and to claim priority under the terms of the International Convention for the Protection of Industrial Property or any other relevant convention;

TIJ and **INVENTOR** hereby authorize and request the Commissioner of Patents to issue U.S. patents for said invention, or U.S. patents resulting therefrom, insofar as the interest of **TIJ** and **INVENTOR** is concerned to the said **TEXAS INSTRUMENTS INCORPORATED**, as assignee of the entire right, title and interest.

TIJ and **INVENTOR** further agree to communicate to **TEXAS INSTRUMENTS INCORPORATED** or to its successors, assigns and legal representatives, any facts known to **TIJ** and **INVENTOR** respecting the said invention, and at the expense of **TEXAS INSTRUMENTS INCORPORATED**, sign any and all patent applications, assignments, affidavits and other lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, testify in any legal or quasi-legal proceedings and generally do everything possible to aid said **TEXAS INSTRUMENTS INCORPORATED**, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries outside of Japan.

A SEMICONDUCTOR DEVICE AND ITS MANUFACTURING METHOD

Title of Invention

Japanese Serial No.: 2000-224,975 Filed: July 26, 2000

U.S. Application Serial No.: 09/909,340 Filed: July 19, 2001

IN WITNESS WHEREOF, this Agreement has been executed as set forth below;

Signed at Tokyo, Japan on August 13, 2001

by **Texas Instruments Japan, Ltd.**

Name 
Toshiaki Ikoma

Title Representative Director and President

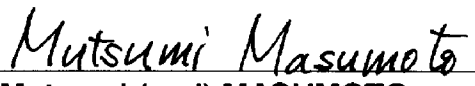
Date 8/13/01

and by the INVENTORS:

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8/9 '01
Date